

**What is claimed is:**

1. A method of making an innerlayer panel, comprising:
  - providing a metallic foil;
  - 5 forming at least one fiducial over the foil;
  - forming at least one feature over the foil;
  - applying a dielectric over the at least one feature and over the at least one fiducial, thereby embedding the at least one fiducial and the at least one feature; and
- 10 identifying the location of the at least one fiducial using X-rays.
2. The method of claim 1, wherein providing a metallic foil comprises:
  - providing a foil comprising copper.
- 15 3. The method of claim 1, wherein forming at least one fiducial comprises:
  - forming at least one fiducial comprising tungsten.
- 20 4. The method of claim 3, wherein the at least one fiducial is formed from a paste containing:
  - glass; and
  - tungsten in excess of 53% by weight.
- 25 5. The method of claim 3, wherein:
  - a dried print thickness of the at least one fiducial is at least 15 microns.
6. The method of claim 1, wherein:
- 30 forming at least one feature and forming at least one fiducial comprise at least one firing step.
7. The method of claim 1, wherein:

forming at least one fiducial comprises curing of a thick-film polymer paste.

8. The method of claim 1, further comprising:
  - 5 applying a second foil to the dielectric before identifying the location of the at least one fiducial;
  - forming at least one register hole in the innerlayer panel according to the identified location of the at least one fiducial;
  - positioning a photo-tool according to the location of the at least 10 one register hole;
  - imaging the foils with the photo-tool; and
  - etching the foils, wherein etching results in terminations for the embedded at least one feature.
- 15 9. The method of claim 1, wherein:
  - the at least one feature comprises at least one capacitor or resistor.
10. The method of claim 1, further comprising:
  - applying an encapsulant over the at least one fiducial prior to 20 applying the dielectric.
11. The method of claim 10, wherein:
  - the dielectric is a prepreg.
- 25 12. A printed wiring board comprising a plurality of stacked innerlayer panels formed by the method of claim 1.
13. An innerlayer panel, comprising:
  - a dielectric;
  - 30 at least one feature at least partially embedded within the dielectric;
  - at least one fiducial at least partially embedded within the dielectric, the fiducial comprising at least one element selected from the group consisting of: tungsten, tantalum, gold, iridium, rhenium, osmium, uranium and platinum; and

at least one conductive termination or associated circuitry in contact with the dielectric and electrically coupled to the at least one feature.

14. The innerlayer panel of claim 13, wherein:
  - 5 the at least one fiducial further comprises glass.
15. The innerlayer panel of claim 13, wherein:
  - the at least one feature comprises at least one of a capacitor and a resistor.
- 10 16. The innerlayer panel of claim 13, further comprising:
  - an encapsulant disposed between the at least one feature and the dielectric.
- 15 17. A printed wiring board comprising a plurality of stacked innerlayer panels of claim 13.